

Kulicke & Soffa Industries, Inc.

Kulicke & Soffa Expands PowerFusionPSTM Wedge Bonders - Introducing the HLx for Wide Leadframe Applications

SINGAPORE--(BUSINESS WIRE)-- Kulicke and Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company") today announced its expanding the PowerFusion^{PS} Wedge Bonders with the HLx model for extra-wide matrix and IPM leadframe applications up to 105mm wide.

The PowerFusion^{PS} Wedge Bonders now come in three different models, with single or multiple head configurations, for a wider variety of choices for customer applications. The PowerFusion^{PS} Bonders are designed for productivity, performance, advanced power semiconductor package capability, ease of use, configuration flexibility and reliability. PowerFusion's productivity reduces manufacturing costs by improving uptimes and higher bond yields, largely contributed by its robust design and innovative features which are optimized for the prevailing and upcoming power semiconductor packaging trends.

- The TL model is the perfect choice for bonding single-row to four-row matrix TO power devices. It is upgradeable to the HL Model in case advanced interconnect requirements are needed in the future.
- The HL Model is specially designed to enable large wire, small wire and PowerRibbon bonding in advanced interconnect designs. Whether bonding high density power devices like SO-8 & PDFN or stretching the wire limit on a matrix D-Pak, the superior indexing accuracy and clamping capabilities of the HL model deliver consistent quality.
- The NEW HLx Model has all the high performance capabilities of the HL Model with the added benefit of handling leadframes up to 105mm wide. Whether there's a current need for wide leadframe processing or just wanting to invest in a flexible platform for future leadframe development, the HLx model is the best choice for many applications.

Chan Pin Chong, Vice President of the K&S Wedge Bonding Business Unit, said, "The PowerFusion^{PS} had a great year of market acceptance this year. With the launch of the HLx Model, it surpasses most of our current customer requests for wider leadframe capability, leaving room for growth in an industry where flexibility is needed for innovative new products. Our customers have shown a high level of interest with our HLx for larger leadframes, and we are expecting to ship the first machines in the next few months."

The PowerFusion^{PS} HLx will debut at the SEMICON Taiwan show at the TWTC Nangang Exhibition Hall, Booth #642, from September 3-5, 2014.

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a global leader in the design and manufacture of semiconductor and LED assembly equipment. As a pioneer in this industry, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions, adding wedge bonding and a broader range of expendable tools to its core ball bonding products. Combined with its extensive expertise in process technology, K&S is well positioned to help customers meet the challenges of assembling the next-generation semiconductor and LED devices. (www.kns.com)

Kulicke and Soffa Industries, Inc.

Sheila Frese

Public Relations

P: +1-949-399-2930

F: +1-949-660-0444

sfrese@kns.com

or

Joseph Elgindy

Investor Relations & Strategic Planning

P: +1-215-784-7518

F: +1-215-784-6180

jelgindy@kns.com

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